Description

Features

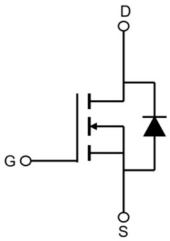
- 200V, 9A
  $R_{DS(ON)}$ < 0.29Ω @ V_{GS} = 10V
- Fast Switching
- Improved dv/dt Capability

Application

- Load Switch
- PWM Application
- Power management

100% UIS
100% ΔVds

TO-252



Schematic Diagram

Package Marking and Ordering Information

Device Marking	Device	OUTLINE	Device Package	Reel Size	Reel (PCS)	Per Carton (PCS)
VSM9N20-T2	VSM9N20	TAPING	TO-252	13inch	2500	25000

Absolute Maximum Ratings (T_C=25℃ unless otherwise specified)

Symbol	Parameter		Max.	Units
V_{DSS}	Drain-Source Voltage		200	V
V_{GSS}	Gate-Source Voltage		±30	V
I_D	Continuous Drain Current	T_C = 25℃	9	A
		T_C = 100℃	5.8	A
I_{DM}	Pulsed Drain Current note1		36	A
E_{AS}	Single Pulsed Avalanche Energy note2		320	mJ
P_D	Power Dissipation	T_C = 25℃	74	W
$R_{\theta JC}$	Thermal Resistance, Junction to Case		1.7	℃/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient		60	℃/W
T_J, T_{STG}	Operating and Storage Temperature Range		-55 to +150	℃

Electrical Characteristics (T_J=25℃ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	V_{GS}=0V, I_D=250μA	200	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS}=200V, V_{GS}=0V, T_J=25℃	-	-	1	μA
I_{GSS}	Gate to Body Leakage Current	V_{DS}=0V, V_{GS}= ±30V	-	-	±100	nA
On Characteristics						
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}=V_{GS}, I_D=250μA	2	-	4	V
$R_{DS(on)}$	Static Drain-Source on-Resistance note3	V_{GS} =10V, I_D =4.5A	-	0.24	0.29	Ω
Dynamic Characteristics						
C_{iss}	Input Capacitance	V_{DS}=25V, V_{GS}=0V, f=1.0MHz	-	684	-	pF
C_{oss}	Output Capacitance		-	103	-	pF
C_{rss}	Reverse Transfer Capacitance		-	37	-	pF
Q_g	Total Gate Charge	V_{DD}=160V, I_D=9A, V_{GS}=10V	-	23	-	nC
Q_{gs}	Gate-Source Charge		-	2.5	-	nC
Q_{gd}	Gate-Drain(“Miller”) Charge		-	10	-	nC
Switching Characteristics						
$t_{d(on)}$	Turn-on Delay Time	V_{DD}=100V, I_D=9A, R_G=25Ω	-	12	-	ns
t_r	Turn-on Rise Time		-	22	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	50	-	ns
t_f	Turn-off Fall Time		-	48	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I_S	Maximum Continuous Drain to Source Diode Forward Current		-	-	9	A
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	36	A
V_{SD}	Drain to Source Diode Forward Voltage	V_{GS}=0V, I_{SD}=9A	-	-	1.4	V
t_{rr}	Reverse Recovery Time	V_{GS}=0V, I_S=9A, di/dt=100A/μs	-	190	-	ns
Q_{rr}	Reverse Recovery Charge		-	1.7	-	μC

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. EAS condition: T_J = 25°C, V_{DD} = 50V, V_G = 10V, L= 10mH, I_{AS} = 8A

3. Pulse Test: Pulse Width≤300μs, Duty Cycle≤1%

Typical Performance Characteristics

Figure1: Output Characteristics

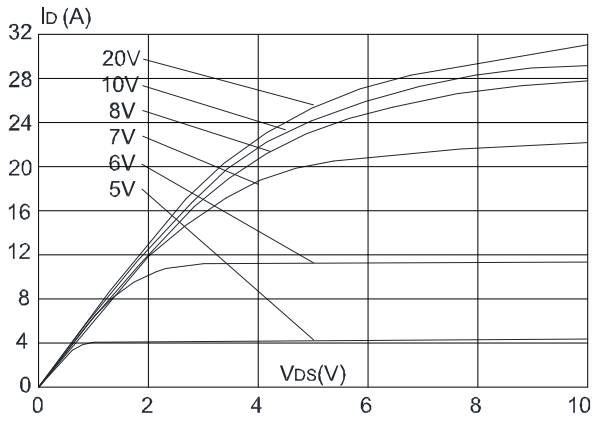


Figure 2: Typical Transfer Characteristics

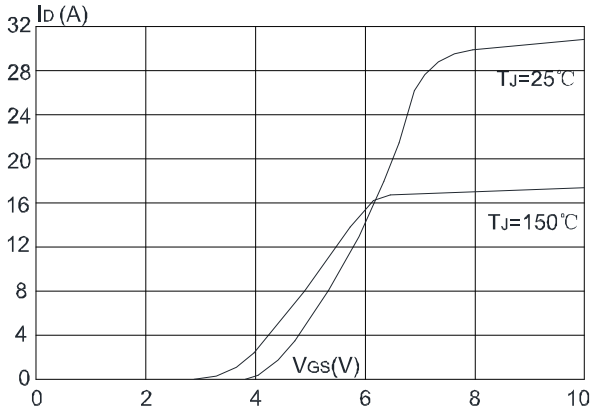


Figure 3: On-resistance vs. Drain Current

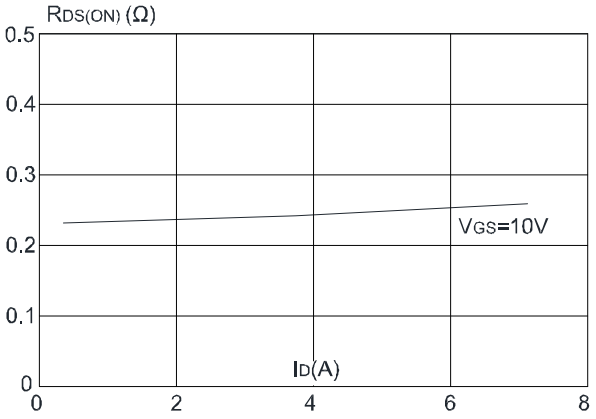


Figure 4: Body Diode Characteristics

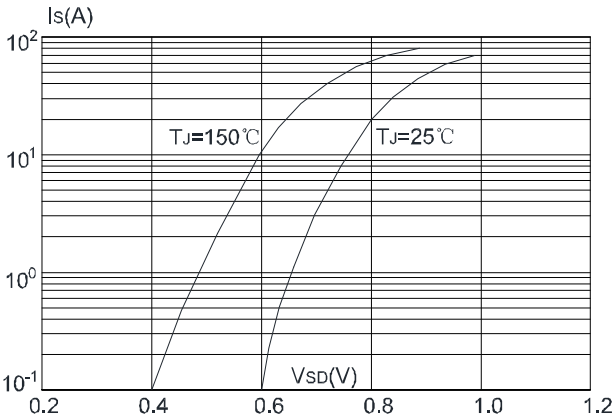


Figure 5: Gate Charge Characteristics

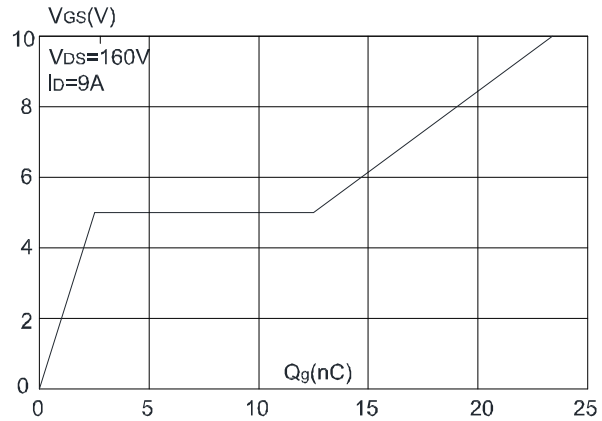


Figure 6: Capacitance Characteristics

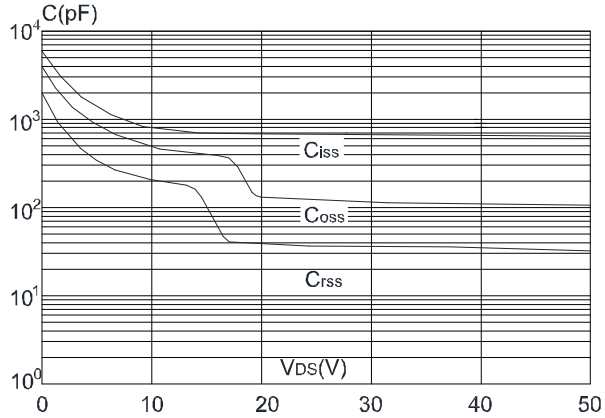


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

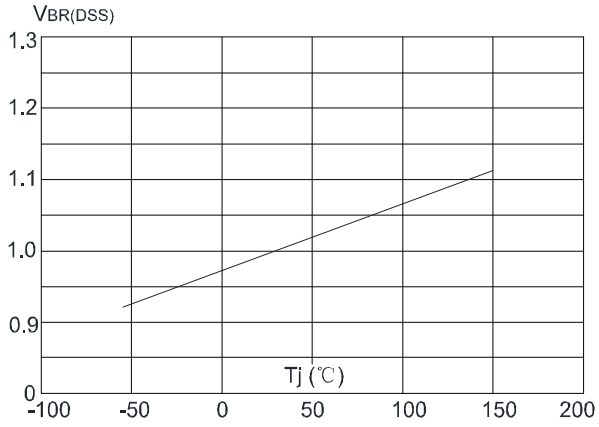


Figure 8: Normalized on Resistance vs. Junction Temperature

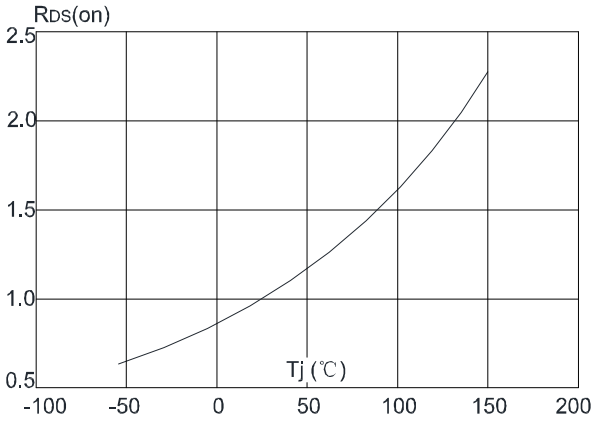


Figure 9: Maximum Safe Operating Area

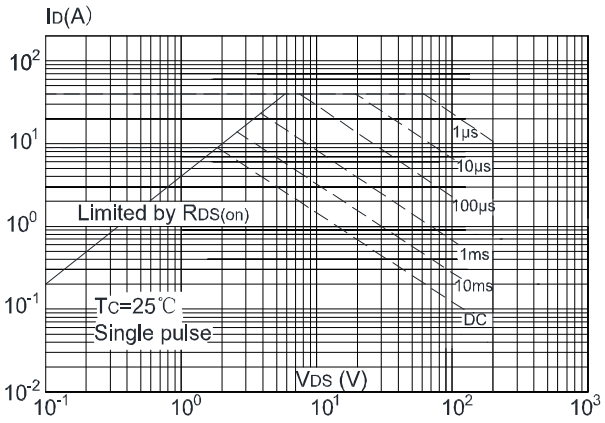


Figure 10: Maximum Continuous Drain Current vs. Case Temperature

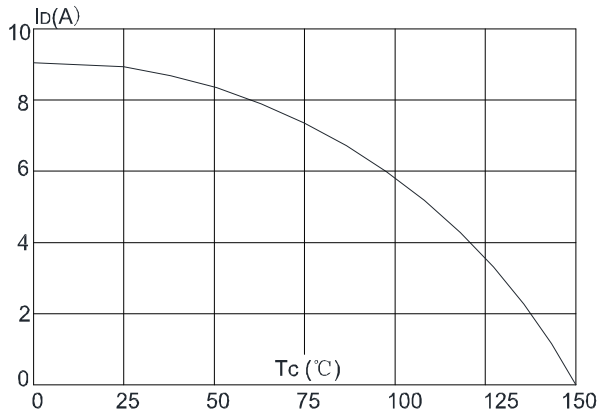
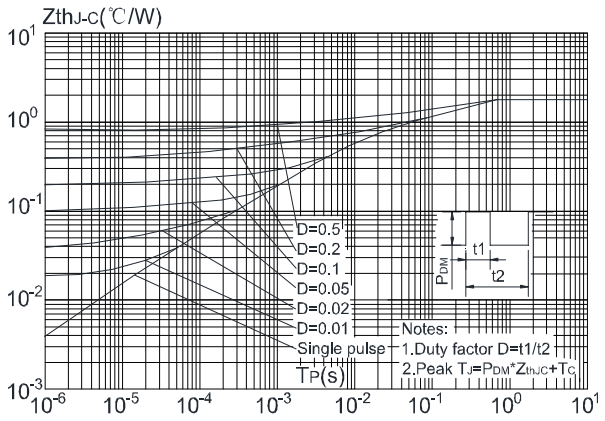


Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Case



Test Circuit

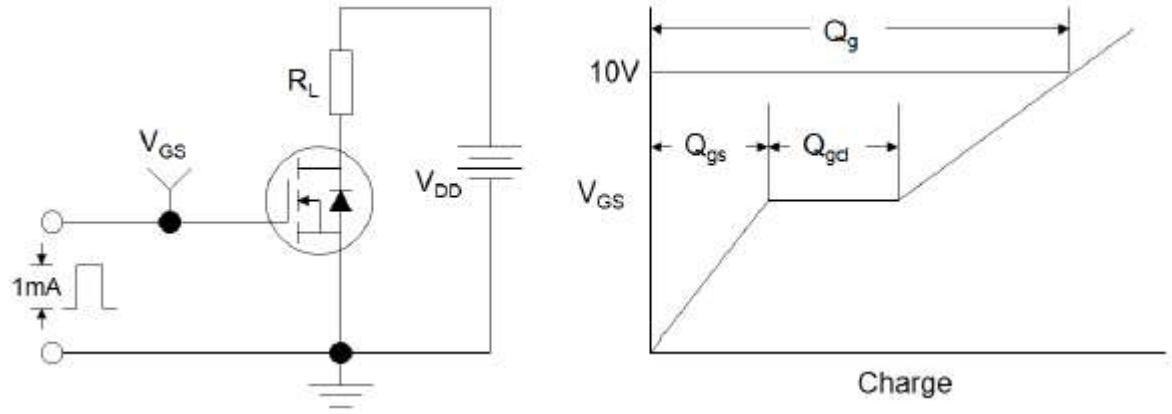


Figure1:Gate Charge Test Circuit & Waveform

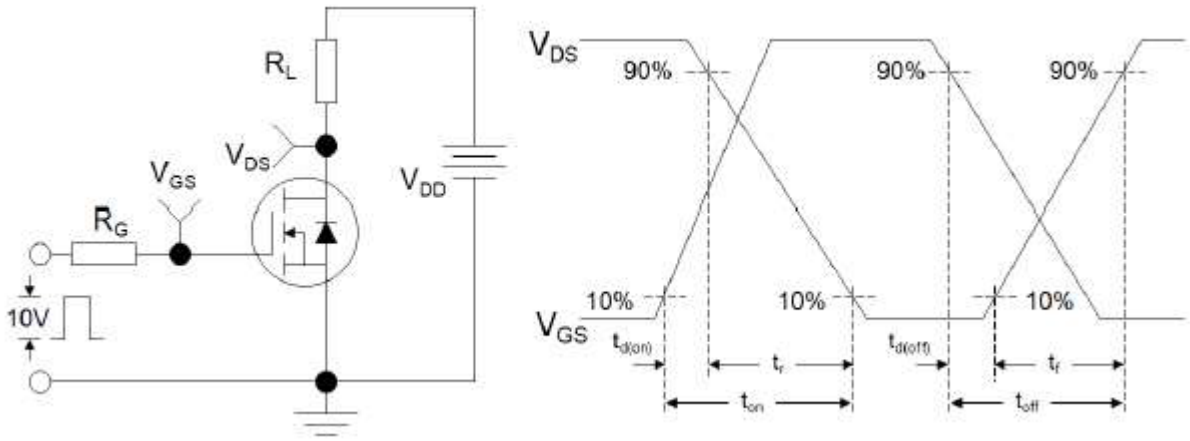


Figure 2: Resistive Switching Test Circuit & Waveforms

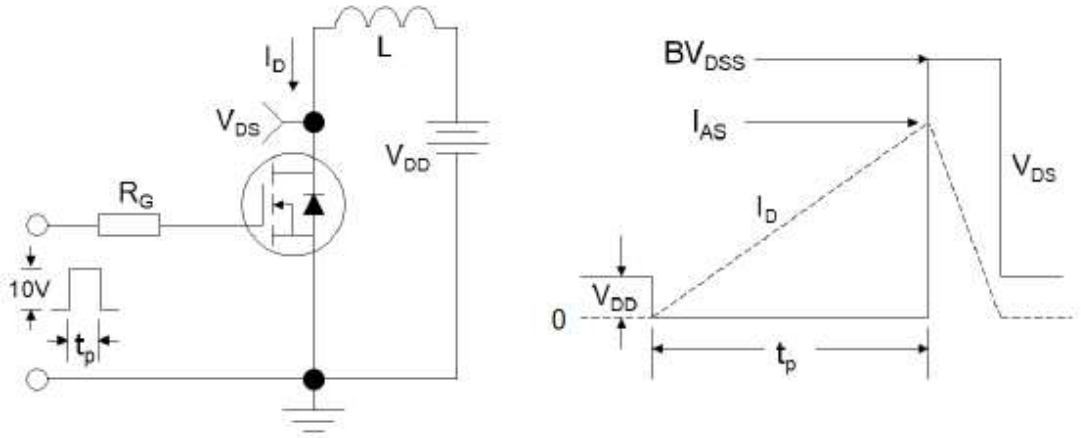


Figure 3:Unclamped Inductive Switching Test Circuit & Waveforms